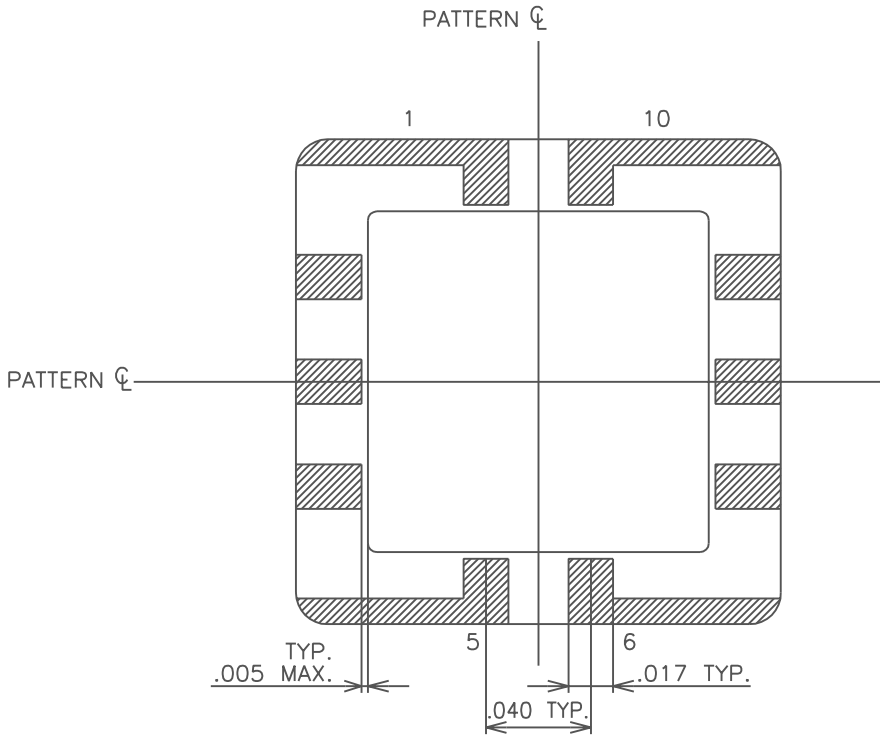


NOTES.

1. GOLD PLATING 60 MICRO INCHES MIN. THICKNESS OVER 100 MICRO INCHES NOMINAL THICKNESS OF NICKEL. UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.15 OHM MAX.

						NAME		TOLERANCE		DRAWN		CHECKED		APPROVED		DATE	
						10 LEAD FLAT PACKAGE		UNLESS OTHERWISE SPECIFIED		T.A		K.M				MAR 10 '78	
						SCALE 8/1		MATERIAL AS INDICATED		±.005							
										THIRD ANGLE PROJECTION							
MODIFICATION		REDRAWN : CONVERTED CAD DATA		MWR&D1		T.S./H.K		SHK/S.M		H.S.A		DRAWING NO.		KYOCERA CORPORATION		SHEET 1/2	
		CHANGED		DATE		DRAWN		CHECKED		APPROVED		KYOCERA		KYOTO JAPAN		KD-F78092-B	





BONDING PATTERN

MODIFICATION						NAME	10 LEAD FLAT PACKAGE	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	20 / 1	UNLESS OTHERWISE SPECIFIED	T.A	K.M		MAR.10.78
						MATERIAL		THIRD ANGLE PROJECTION				
△	REDRAWN	MAR.8.'01	T.S/H.K	SH.K/S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-F78092-B		SHEET	2 / 2
	CHANGED	DATE	DRAWN	CHECKED	APPROVED							

